

## High-Speed CMOS Logic Hex D-Type Flip-Flop with Reset

### Features

- Buffered Positive Edge Triggered Clock
- Asynchronous Common Reset
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The 'HC174 and 'HCT174 are edge triggered flip-flops which utilize silicon gate CMOS circuitry to implement D-type flip-flops. They possess low power and speeds comparable to low power Schottky TTL circuits. The devices contain six master-slave flip-flops with a common clock and common reset. Data on the D input having the specified setup and hold

times is transferred to the Q output on the low to high transition of the CLOCK input. The MR input, when low, sets all outputs to a low state.

Each output can drive ten low power Schottky TTL equivalent loads. The 'HCT174 is functional as well as, pin compatible to the 'LS174.

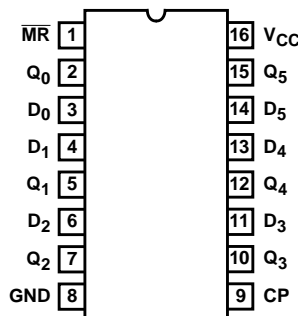
### Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC174F3A	-55 to 125	16 Ld CERDIP
CD54HCT174F3A	-55 to 125	16 Ld CERDIP
CD74HC174E	-55 to 125	16 Ld PDIP
CD74HC174M	-55 to 125	16 Ld SOIC
CD74HC174MT	-55 to 125	16 Ld SOIC
CD74HC174M96	-55 to 125	16 Ld SOIC
CD74HCT174E	-55 to 125	16 Ld PDIP
CD74HCT174M	-55 to 125	16 Ld SOIC
CD74HCT174MT	-55 to 125	16 Ld SOIC
CD74HCT174M96	-55 to 125	16 Ld SOIC

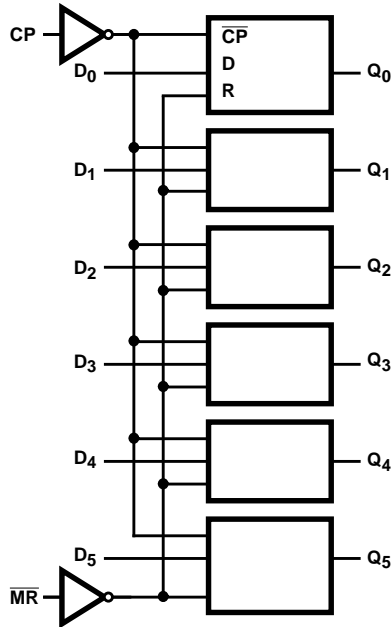
NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

### Pinout

CD54HC174, CD54HCT174  
(CERDIP)  
CD74HC174, CD74HCT174  
(PDIP, SOIC)  
TOP VIEW



**Functional Diagram**

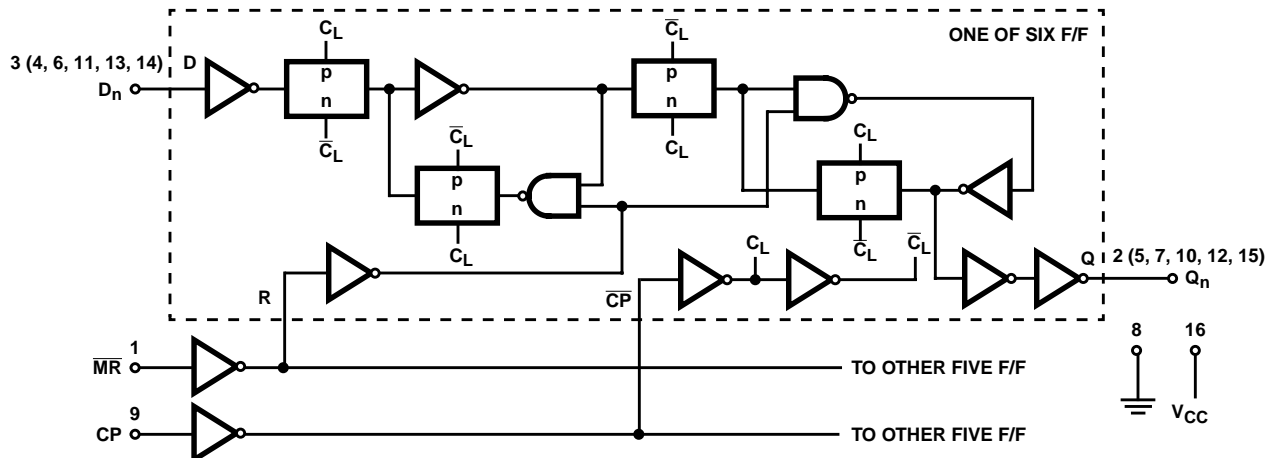


TRUTH TABLE

INPUTS			OUTPUT
RESET ( $\overline{MR}$ )	CLOCK CP	DATA $D_n$	$Q_n$
L	X	X	L
H	$\uparrow$	H	H
H	$\uparrow$	L	L
H	L	X	$Q_0$

H = High Voltage Level, L = Low Voltage Level, X = Irrelevant,  $\uparrow$  = Transition from Low to High Level,  $Q_0$  = Level Before the Indicated Steady-State Input Conditions Were Established

**Logic Diagram**



# CD54HC174, CD74HC174, CD54HCT174, CD74HCT174

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ .....	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 1)	$\theta_{JA}$ ( $^{\circ}C/W$ )
E (PDIP) Package .....	67
M (SOIC) Package .....	73
Maximum Junction Temperature .....	150 $^{\circ}C$
Maximum Storage Temperature Range .....	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s) .....	300 $^{\circ}C$ (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range ( $T_A$ ) .....	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	
HC Types .....	.2V to 6V
HCT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25 $^{\circ}C$			-40 $^{\circ}C$ TO +85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$
Quiescent Device Current	$I_{CC}$	$V_{CC}$ or GND	0	6	-	-	8	-	80	-	160	$\mu A$

**CD54HC174, CD74HC174, CD54HCT174, CD74HCT174**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO +85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> to GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 2)	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

- For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

INPUT	UNIT LOADS
CP	0.80
MR	0.55
D	0.15

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Specifications table, e.g. 360μA max at 25°C.

**Prerequisite For Switching Function**

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>										
Clock Pulse Width	t <sub>w</sub>	-	2	80	-	100	-	120	-	ns
			4.5	16	-	20	-	24	-	ns
			6	14	-	17	-	20	-	ns
MR Pulse Width	t <sub>w</sub>	-	2	80	-	100	-	120	-	ns
			4.5	16	-	20	-	24	-	ns
			6	14	-	17	-	20	-	ns

**CD54HC174, CD74HC174, CD54HCT174, CD74HCT174**

**Prerequisite For Switching Function (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	MAX	MIN	MAX	MIN	MAX	
Setup Time, Data to Clock	t <sub>SU</sub>	-	2	60	-	75	-	90	-	ns
			4.5	12	-	15	-	18	-	ns
			6	10	-	13	-	15	-	ns
Hold Time, Data to Clock	t <sub>H</sub>	-	2	5	-	5	-	5	-	ns
			4.5	5	-	5	-	5	-	ns
			6	5	-	5	-	5	-	ns
Removal Time, $\overline{MR}$ to Clock	t <sub>REM</sub>	-	2	5	-	5	-	5	-	ns
			4.5	5	-	5	-	5	-	ns
			6	5	-	5	-	5	-	ns
Clock Frequency	f <sub>MAX</sub>	-	2	6	-	5	-	4	-	MHz
			4.5	30	-	24	-	20	-	MHz
			6	35	-	28	-	24	-	MHz

**HCT TYPES**

Clock Pulse Width	t <sub>w</sub>	-	4.5	20	-	25	-	30	-	ns
$\overline{MR}$ Pulse Width	t <sub>w</sub>	-	6	25	-	31	-	38	-	ns
Setup Time, Data to Clock	t <sub>SU</sub>	-	4.5	16	-	20	-	24	-	ns
Hold Time, Data to Clock	t <sub>H</sub>	-	6	5	-	5	-	5	-	ns
Removal Time, $\overline{MR}$ to Clock	t <sub>REM</sub>	-	4.5	12	-	15	-	18	-	ns
Clock Frequency	f <sub>MAX</sub>	-	6	25	-	20	-	17	-	MHz

**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
Propagation Delay, Clock to Q	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	165	205	250	ns
			4.5	-	33	41	50	ns
			6	-	28	35	43	ns
		C <sub>L</sub> = 15pF	5	13	-	-	-	ns
Propagation Delay, $\overline{MR}$ to Q	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	150	190	225	ns
			4.5	-	30	38	45	ns
			6	-	26	33	38	ns
		C <sub>L</sub> = 15pF	5	12	-	-	-	ns
Output Transition Times	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	75	95	110	ns
			4.5	-	15	19	22	ns
			6	-	13	16	19	ns
Input Capacitance	C <sub>IN</sub>	-	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C <sub>PD</sub>	-	5	38	-	-	-	pF

**CD54HC174, CD74HC174, CD54HCT174, CD74HCT174**

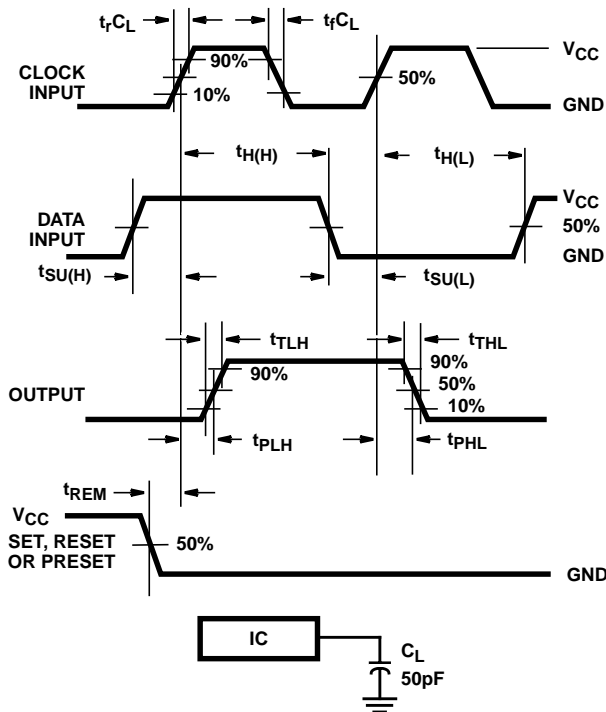
**Switching Specifications** Input  $t_r, t_f = 6\text{ns}$  (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
<b>HCT TYPES</b>								
Propagation Delay, Clock to Q	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	40	50	60	ns
			5	17	-	-	-	ns
Propagation Delay, $\overline{MR}$ to Q	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	44	55	66	ns
			5	18	-	-	-	ns
Output Transition Times	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	15	19	22	ns
Input Capacitance	$C_{IN}$	-	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	-	5	44	-	-	-	pF

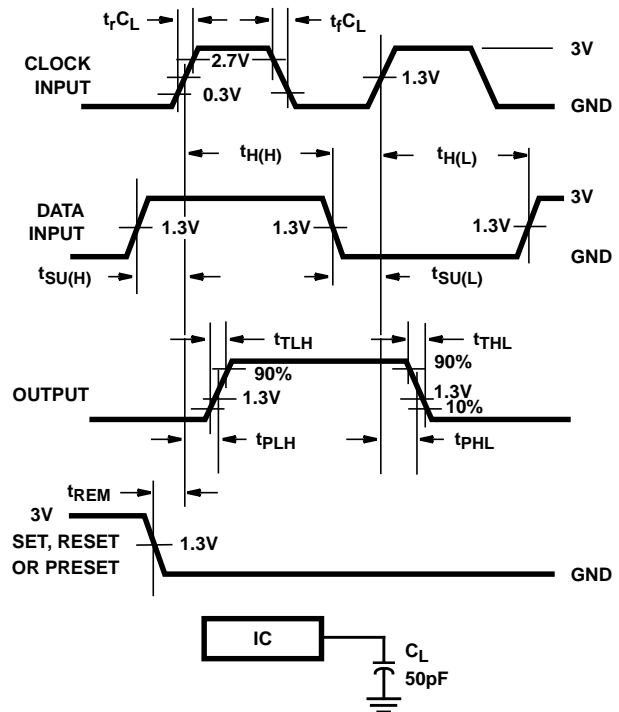
**NOTES:**

- $C_{PD}$  is used to determine the dynamic power consumption, per flip-flop.
- $P_D = V_{CC}^2 f_i + \sum (C_L V_{CC}^2 + f_O)$  where  $f_i$  = Input Frequency,  $f_O$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

**Test Circuits and Waveforms**



**FIGURE 1. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS**



**FIGURE 2. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8974301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8974301EA CD54HCT174F3A	<a href="#">Samples</a>
CD54HC174F	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54HC174F	<a href="#">Samples</a>
CD54HC174F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8407301EA CD54HC174F3A	<a href="#">Samples</a>
CD54HCT174F	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54HCT174F	<a href="#">Samples</a>
CD54HCT174F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8974301EA CD54HCT174F3A	<a href="#">Samples</a>
CD74HC174E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC174E	<a href="#">Samples</a>
CD74HC174M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC174M	<a href="#">Samples</a>
CD74HC174M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC174M	<a href="#">Samples</a>
CD74HC174M96E4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC174M	<a href="#">Samples</a>
CD74HC174MG4	ACTIVE	SOIC	D	16	40	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT174E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT174E	<a href="#">Samples</a>
CD74HCT174EE4	ACTIVE	PDIP	N	16	25	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT174M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT174M	<a href="#">Samples</a>
CD74HCT174M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT174M	<a href="#">Samples</a>
CD74HCT174M96G4	ACTIVE	SOIC	D	16	2500	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT174MG4	ACTIVE	SOIC	D	16	40	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HCT174MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT174M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF CD54HC174, CD54HCT174, CD74HC174, CD74HCT174 :**

● Catalog : [CD74HC174](#), [CD74HCT174](#)

● Military : [CD54HC174](#), [CD54HCT174](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product



- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

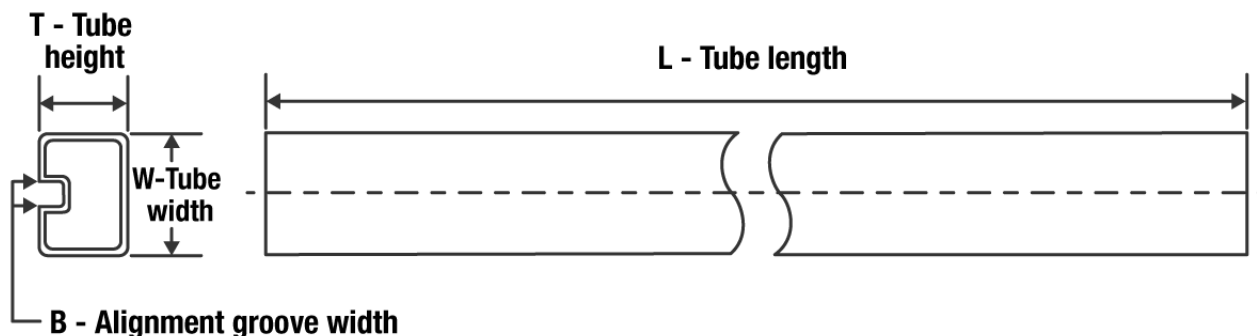

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC174M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT174M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC174M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HCT174M96	SOIC	D	16	2500	340.5	336.1	32.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74HC174E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC174E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC174M	D	SOIC	16	40	507	8	3940	4.32
CD74HC174MG4	D	SOIC	16	40	507	8	3940	4.32
CD74HCT174E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT174E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT174EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT174EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT174M	D	SOIC	16	40	507	8	3940	4.32
CD74HCT174MG4	D	SOIC	16	40	507	8	3940	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



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